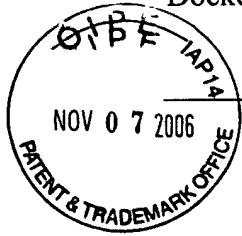


Iiw

Please Direct All Correspondence to Customer Number **20995****AMENDMENT / RESPONSE TRANSMITTAL**

Applicant : Basol et al.
App. No : 10/782,697
Filed : February 18, 2004
For : METHOD OF WAFER PROCESSING
WITH EDGE SEED LAYER
REMOVAL
Examiner : Michael Manh Trinh
Art Unit : 2822

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

November 2, 2006

(Date)

Tina Chen, Reg. No. 44,606

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450


Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing in the above-identified application are the following enclosures:

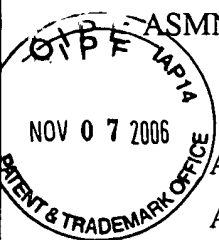
- (X) Response to Restriction Requirement in 6 pages.
- (X) Return prepaid postcard.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.


Tina Chen
Registration No. 44,606
Attorney of Record
Customer No. 20,995
(415) 954-4114

PAT-AMENDTRANS

3080084
110206



ASMNUT.031CP1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Basol et al.
Appl. No. : 10/782,697
Filed : February 18, 2004
For : METHOD OF WAFER
PROCESSING WITH EDGE
SEED LAYER REMOVAL
Examiner : Michael Manh Trinh
Group Art Unit : 2822

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

November 2, 2006

(Date)

Tina Chen, Reg. No. 44,606

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In an action mailed October 3, 2006, the Examiner required restriction to one of the following groups:

- I. Claims 11-15, drawn to a method of selectively removing a seed layer from a wafer using a process solution, classified in 438/747.
- II. Claims 1-10, 16-21, 22-24, drawn to a method for forming a conductive material on a wafer, classified in Class 438/584.

The Examiner also required a further election between the following subgroups if Group II is elected:

SubGroup IIa: Claims 1-10, 16-21

SubGroup IIb: Claims 22-24

In response, Applicants elect, without traverse, to proceed with examination on the merits of SubGroup IIa (Claims 1-10, 16-21).

Appl. No. : **10/782,697**
Filed : **February 18, 2004**

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 6 of this paper.